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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10003114	FILING DATE 12/06/2001	CLASS 438	SUBCLASS 049	GAU 2812	EXAMINER J. A. Greene
**APPLICANTS: Yamada Masaki; Kajita Akihiro;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN P2001-298522 09/27/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 216932US2	
Verified and Acknowledged Examiners's initials					
TITLE : Semiconductor device having buried conductive layer and method of manufacturing thereof					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
			Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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